§6. Development of Ion Source for Thin Film Formation

Henry J. Ramos (NIP, Univ. Philippines) Taniike, A., Sasao, M., Wada, M. (Doshisha Univ.)

We have developed a plasma-sputter-type negative ion source which is not only useful as an ion source of tandem-type heavy ion beam probe for the Large Helical Device but also for ion beam application such as ion implantation or thin film formation. In the present study, a one liter volume

ion source to study Au⁻ is used by changing the gold target to a titanium target. The experimental setup is shown in Fig. 1. The produced Ti⁻ beam is collimated into a reaction chamber with nitrogen gas. The resulting interaction of the ion beam and nitrogen on silicon substrate in investigated. The use of a plasma-sputter-type negative ion source presents a new approach for the production of high grade coatings like TiN.

The ion source was operated at typical base pressure of $1.8 \times 10-6$ Torr. A xenon arc plasma was produced at 2.0 x 10-4 Torr. Typical operating parameters for the discharge are: discharge current = 4mA, Discharge voltage = 30 V, filament current 12 A, and target potential = -300 V. The ion beam has a typical energy width of 9eV with a characteristic negative ion current of several tens of nanoamperes. In this development,

the beam characteristics of Ti as functions of operating conditions like the discharge voltage, discharge current, beam acceleration voltage, lens voltage and target voltage were examined as shown in Fig. 2-4. Because of the low electron affinity of titanium, the Ti yield should be expected to be very low. In order to obtain a significant amount of beam flux onto a target chamber, added features like a beam deflector and a lens system have been developed and incorporated in the experimental setup. By property operating the lens system, a higher Ticurrent at the reaction chamber and an increase of the probability of interaction on the subtrate surface. This means a shorter time for film deposition in the reaction chamber.

